

HIGH PERFORMANCE COMPUTING FOR MANUFACTURING INTERNSHIP PROGRAM

HPC 4 MFG

DETAILS

- 10 consecutive weeks between May and September 2021.
- Stipend:
 - Undergraduate students \$600/week
 - Graduate students \$750/week.
- Travel reimbursement for up to \$1000*
- Housing Allowance of \$150/week*

*If living more than fifty miles, one-way, from assigned hosting laboratory

ELIGIBILITY

- Be a U.S. citizen AND at least 18 years old by May 1, 2021.
- Open to recent graduates, undergraduate and graduate students. Have or be pursuing a degree related to high performance computing.

APPLICATION DEADLINE

February 1, 2021 | 4 PM EST

APPLY NOW

[HTTPS://WWW.ZINTELLECT.COM/OPPORTUNITY/DETAILS/DOE-EERE-HPC-2021](https://www.zintellect.com/opportunity/details/doe-eere-hpc-2021)

The HPC4Mfg Internship Program is sponsored by the Advanced Manufacturing Office (AMO) within the Office of Energy Efficiency & Renewable Energy.

